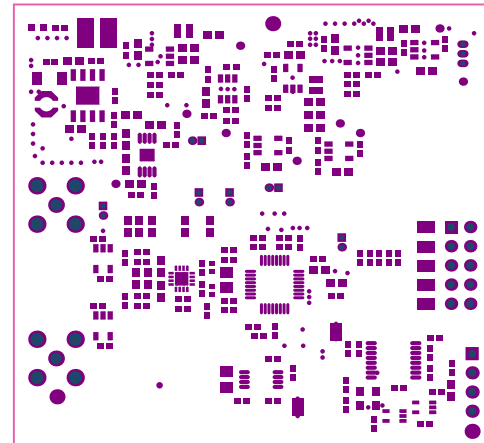
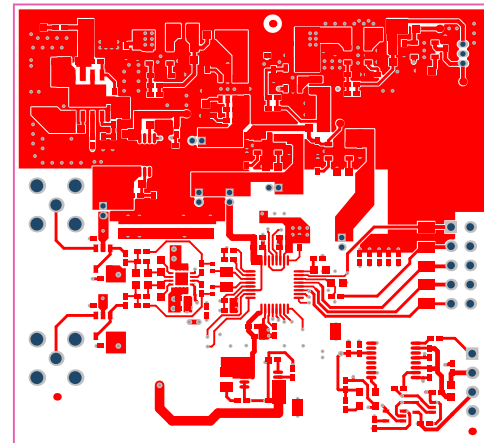


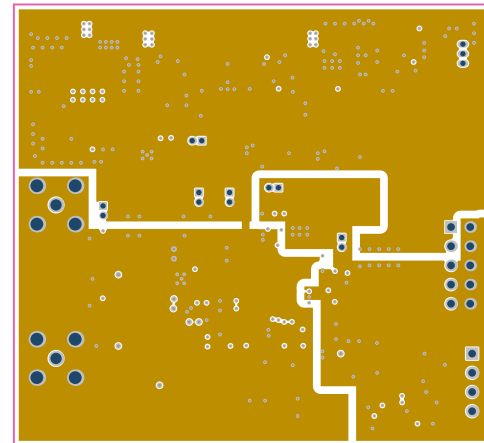
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01013	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDA-01013		
PLOT NAME = Top Overlay	GENERATED : 6/29/2017 9:49:04 AM	TEXAS INSTRUMENTS	



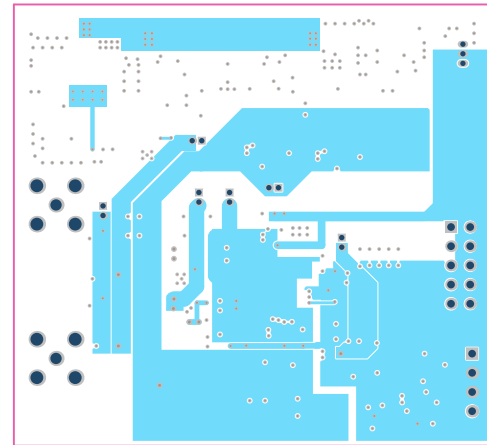
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01013	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-01013		
PLOT NAME = Top Solder Mask	GENERATED : 6/29/2017 9:49:08 AM	TEXAS INSTRUMENTS	



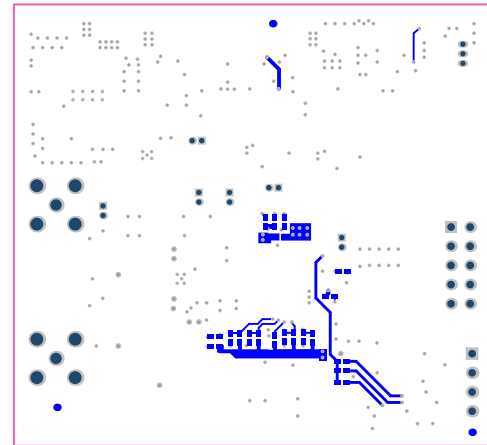
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01013	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: TIDA-01013		
PLOT NAME = Top Layer	GENERATED : 6/29/2017 9:49:12 AM	TEXAS INSTRUMENTS	



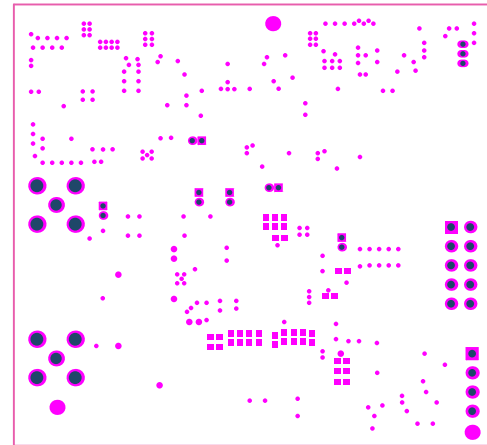
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01013	REV: E1	SVN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01013		
PLOT NAME = Signal Layer 1	GENERATED : 6/29/2017 9:49:15 AM	TEXAS INSTRUMENTS	



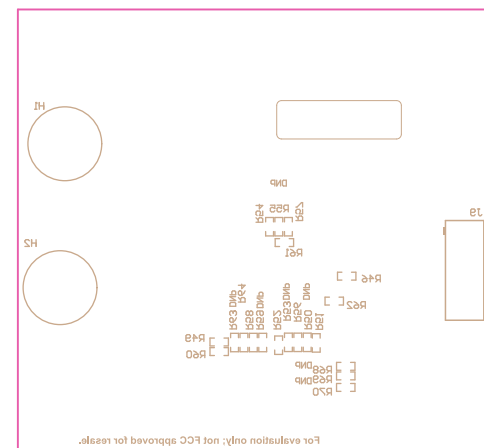
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01013	REV: E1	SVN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01013		
PLOT NAME = Signal Layer 2	GENERATED : 6/29/2017 9:49:19 AM	TEXAS INSTRUMENTS	



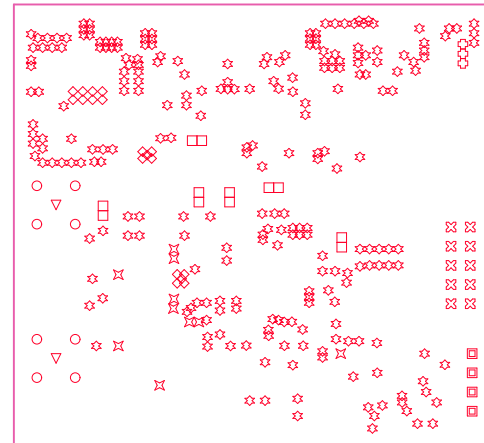
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01013	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: TIDA-01013		
PLOT NAME = Bottom Layer	GENERATED : 6/29/2017 9:49:23 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01013	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-01013		
PLOT NAME = Bottom Solder Mask	GENERATED : 6/29/2017 9:49:27 AM	TEXAS INSTRUMENTS	

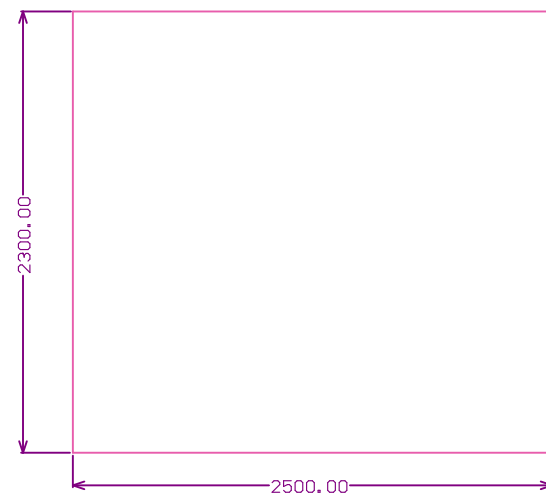


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01013	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDA-01013		
PLOT NAME = Bottom Overlay	GENERATED : 6/29/2017 9:49:31 AM	TEXAS INSTRUMENTS	



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
◇	18	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
☆	247	10.00mil (0.254mm)	PTH	Round	Top Layer - Bottom Layer	
✕	10	15.00mil (0.381mm)	PTH	Round	Top Layer - Bottom Layer	
⊕	3	27.56mil (0.700mm)	PTH	Round	Top Layer - Bottom Layer	
□	12	28.00mil (0.711mm)	PTH	Round	Top Layer - Bottom Layer	
■	4	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	10	40.16mil (1.020mm)	PTH	Round	Top Layer - Bottom Layer	
▽	2	59.06mil (1.500mm)	PTH	Round	Top Layer - Bottom Layer	
○	8	66.93mil (1.700mm)	PTH	Round	Top Layer - Bottom Layer	
	314 Total					

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01013	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-01013		
PLOT NAME = Drill Drawing	GENERATED : 6/29/2017 9:49:35 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01013	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: TIDA-01013		
PLOT NAME = Board Dimensions	GENERATED : 6/29/2017 9:49:39 AM	TEXAS INSTRUMENTS	

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